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**PATENT ABSTRACTS OF JAPAN**(21) Application number: **09305884**(51) Intl. Cl.: **B24B 37/00**(22) Application date: **07.11.97**

(30) Priority:		(71) Applicant: <b>NIKON CORP</b>
(43) Date of application publication:	<b>25.05.99</b>	(72) Inventor: <b>ISHIKAWA AKIRA</b>
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**(54) CMP POLISHING PAD  
AND POLISHING DEVICE  
USING IT**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a CMP polishing pad which is not affected by dissolution and corrosion due to polishing agent.

SOLUTION: A CMP polishing pad 10 mainly contains A and B components, including bisphenol A epoxy resin, novolak epoxy resin, bisphenol F epoxy resin, or these polymer and these deformed epoxy resin, aromatic amines, aromatic acid anhydride, imidazols, or these polymer and these deformed hardening agent, the surface hardness being 2.5-40 at a Vickers hardness.

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